

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yasushi NODA</td> <td>03/07/2013</td> </tr> <tr> <td>Hiromasa SATO</td> <td>03/11/2013</td> </tr> </tbody> </table>		Name	Execution Date	Yasushi NODA	03/07/2013	Hiromasa SATO	03/11/2013
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Yasushi NODA	03/07/2013						
Hiromasa SATO	03/11/2013						
RECEIVING PARTY DATA							
Name:	MEIDEN T&D CORPORATION						
Street Address:	1-1, Osaki 2-chome						
City:	Shinagawa-ku, Tokyo						
State/Country:	JAPAN						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13806568</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13806568		
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Application Number:	13806568						
CORRESPONDENCE DATA							
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Date:	04/17/2013						
Total Attachments: 1 source=65202US_Assignment#page1.tif							

OP \$40.00 13806568

PATENT

ASSIGNMENT

(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me or us citizen(s) of Japan by MEIDEN T&D CORPORATION, a corporation organized under the laws of Japan, located at 1-1, Osaki 2-chome, Shinagawa-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said MEIDEN T&D CORPORATION, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

METHOD FOR PRODUCING ELECTRODE MATERIAL FOR VACUUM CIRCUIT BREAKER, ELECTRODE MATERIAL FOR VACUUM CIRCUIT BREAKER AND ELECTRODE FOR VACUUM CIRCUIT BREAKER

invented by me or us and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said MEIDEN T&D CORPORATION, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said MEIDEN T&D CORPORATION.

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) Yasushi NODA <i>Yasushi Noda</i>	<u>03/07/2013</u>
2) Hiromasa SATO <i>Hiromasa Sato</i>	<u>03/11/2013</u>
3)	
4)	
5)	
6)	
7)	
8)	
9)	
10)	